

IN THE SPECIFICATION:

Please amend paragraph [0011] as shown below.

In one embodiment, DUT 20 may be a high performance processor, for example. During operation, DUT 20 may output signals on a variety of contacts, such as contact 21. As described in greater detail below, in one embodiment, to capture and analyze the output signals on analyzer 50 the signals may be routed to analyzer 50 through an interposer [60] 160 and a test board (not shown in FIG. 1) 170. As will be described in greater detail below in conjunction with the description of FIG. 2, interposer 160 may include a plurality of contact pins (not shown in FIG. 1) which convey the signals.

Please amend paragraph [0014] as shown below.

Backing plate 180 may be used to provide a compressive force for “sandwiching” test board 170, interposer 160, system board 150, DUT 20 and heat sink 120 together. In the illustrated embodiment, thumb-screws 21 or other suitable fasteners may be used to fasten backing plate 180 to heat sink 120. This arrangement may compress each contact on DUT 20, interposer 160 and test chip 40 to their respective contact pads on their respective circuit boards.

Please amend paragraph [0015] as shown below.

In the illustrated embodiment, DUT 20 uses a ball grid array (BGA) for its contact pinout. The BGA forms a given footprint pattern. The footprint pattern 125 of DUT 20 is mated to a footprint pattern 155 on system board 150. Footprint pattern 155 is provided on both the top and bottom surface of system board 150. To keep lead lengths as short as possible, the footprint pattern on each board surface is symmetrically matching and also positioned opposite each other. Accordingly, a footprint pattern on the bottom surface of interposer 160 mates to footprint pattern 155 on the top surface of

system board 150. In addition, a footprint pattern on the top surface of interposer 160 mates to a footprint pattern on the bottom surface of test board 170, and so forth. It is noted that although a BGA footprint pattern 125 is used in the illustrated embodiment, other embodiments are contemplated in which other footprint patterns may be used.